Technical Data Sheet

Reverse Package Top LEDs

67-21 SUGC/S400-XX/TR10

Features

- P-LCC-2 package.
- White package.
- Optical indicator.
- Colorless clear window.
- Wide viewing angle.
- Suitable for vapor-phase reflow, Infrared reflow and wave solder processes.
- Computable with automatic placement equipment.
- Available on tape and reel (12mm Tape).
- Pb-free.
- The product itself will remain within RoHS compliant version.

Descriptions

- The 67-21 series is available in soft orange, green,blue and yellow. Due to the package design, the LED has wide viewing angle and optimized light coupling by inter reflector. This feature makes the ideal for light pipe application. The low current requirement makes this device ideal for portable equipment or any other application where power is at a premium.

Applications

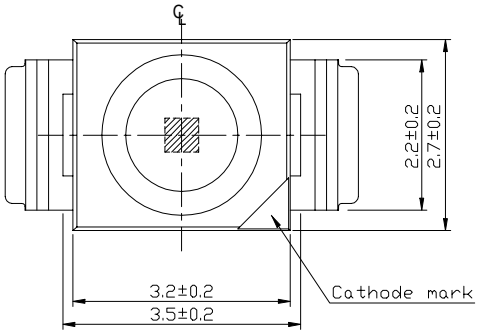
- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- Light pipe application.
- General use.

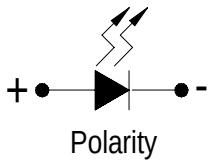
Device Selection Guide

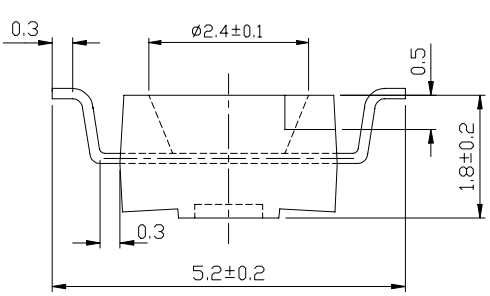
Chip		Lens Color
Material	Emitted Color	
InGaN	Brilliant Green	Water Clear

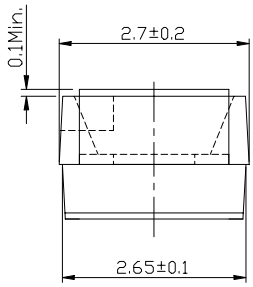
67-21 SUGC/S400-XX/TR10

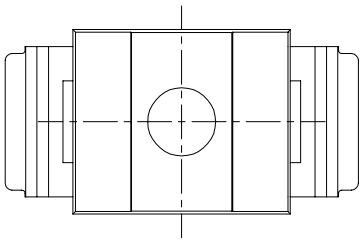
Package Dimensions



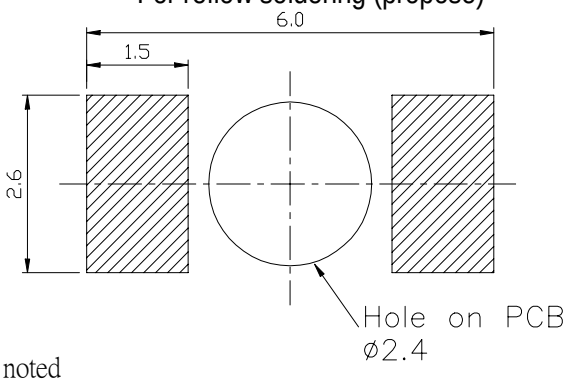








For reflow soldering (propose)



Note :
Tolerances dimension ±0.1 unless otherwise noted
Unit : mm

67-21 SUGC/S400-XX/TR10

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	25	mA
Operating Temperature	Topr	-40 ~ +85	℃
Storage Temperature	Tstg	-40 ~ +90	℃
Electrostatic Discharge(HBM)	ESD	150	V
Power Dissipation	Pd	110	mW
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	100	mA
Soldering Temperature	Tsol	Reflow Soldering : 260 ℃ for 10 sec. Hand Soldering : 350 ℃ for 3 sec.	

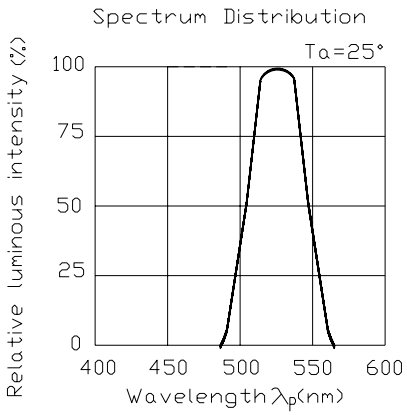
Electro-Optical Characteristics (Ta=25℃)

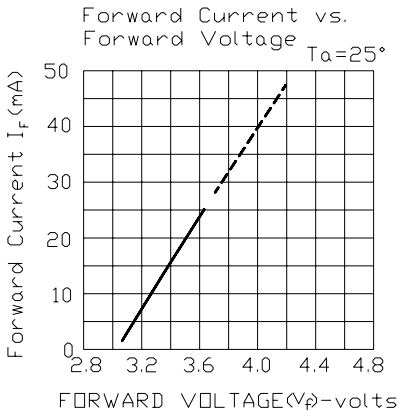
Parameter	Symbol	*Chip Rank.	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	A4	150	279	-----	mcd	I_F=20mA
		A5	250	432			
		X6	300	500			
Viewing Angle	2θ 1/2	-----	-----	120	-----	deg	I_F=20mA
Peak Wavelength	λp	-----	-----	518	-----	nm	I_F=20mA
Dominant Wavelength	λd	-----	-----	525	-----	nm	I_F=20mA
Spectrum Radiation Bandwidth	Δλ	-----	-----	35	-----	nm	I_F=20mA
Forward Voltage	V_F	-----	-----	3.5	4.3	V	I_F=20mA
Reverse Current	I_R	-----	-----	-----	50	μA	V_R=5V

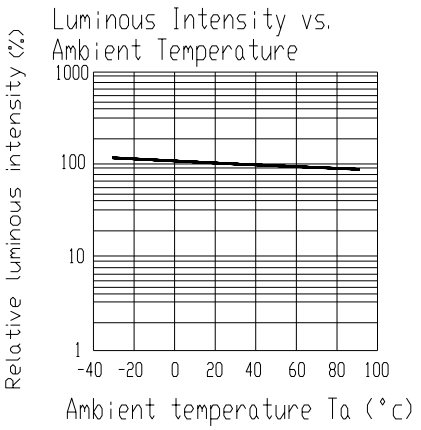
***67-21SUGC/S400-XX/TR10**

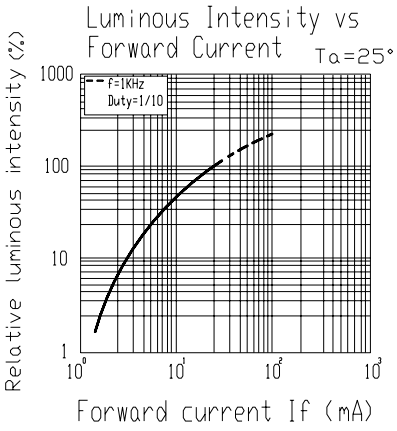
Chip Rank

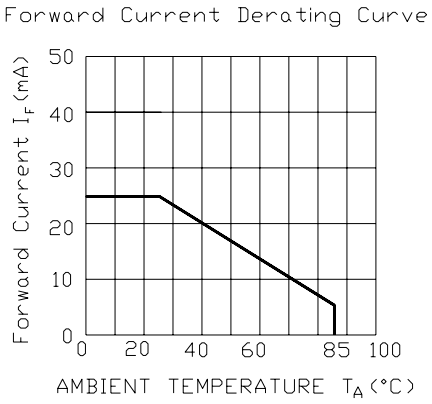
Typical Electro-Optical Characteristics Curves

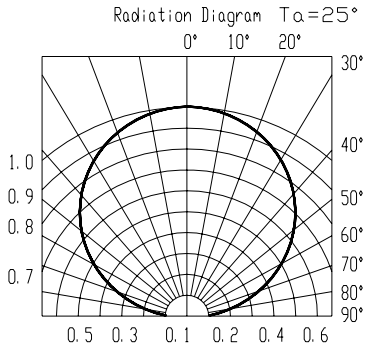












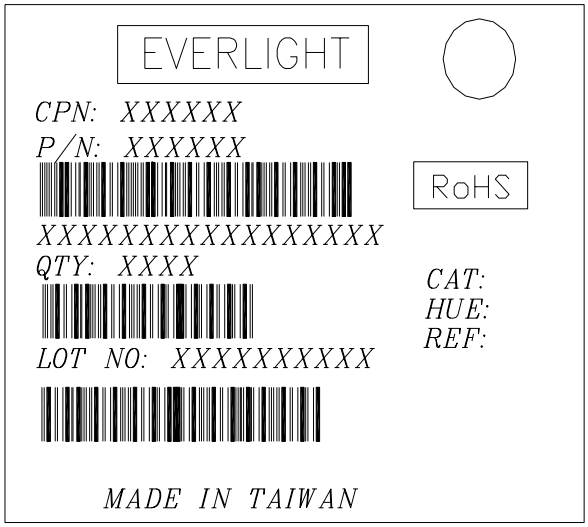
67-21 SUGC/S400-XX/TR10

Label explanation

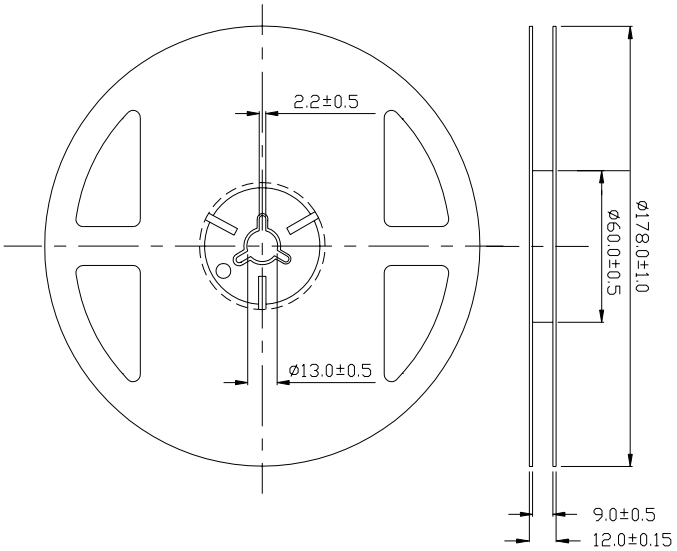
CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank

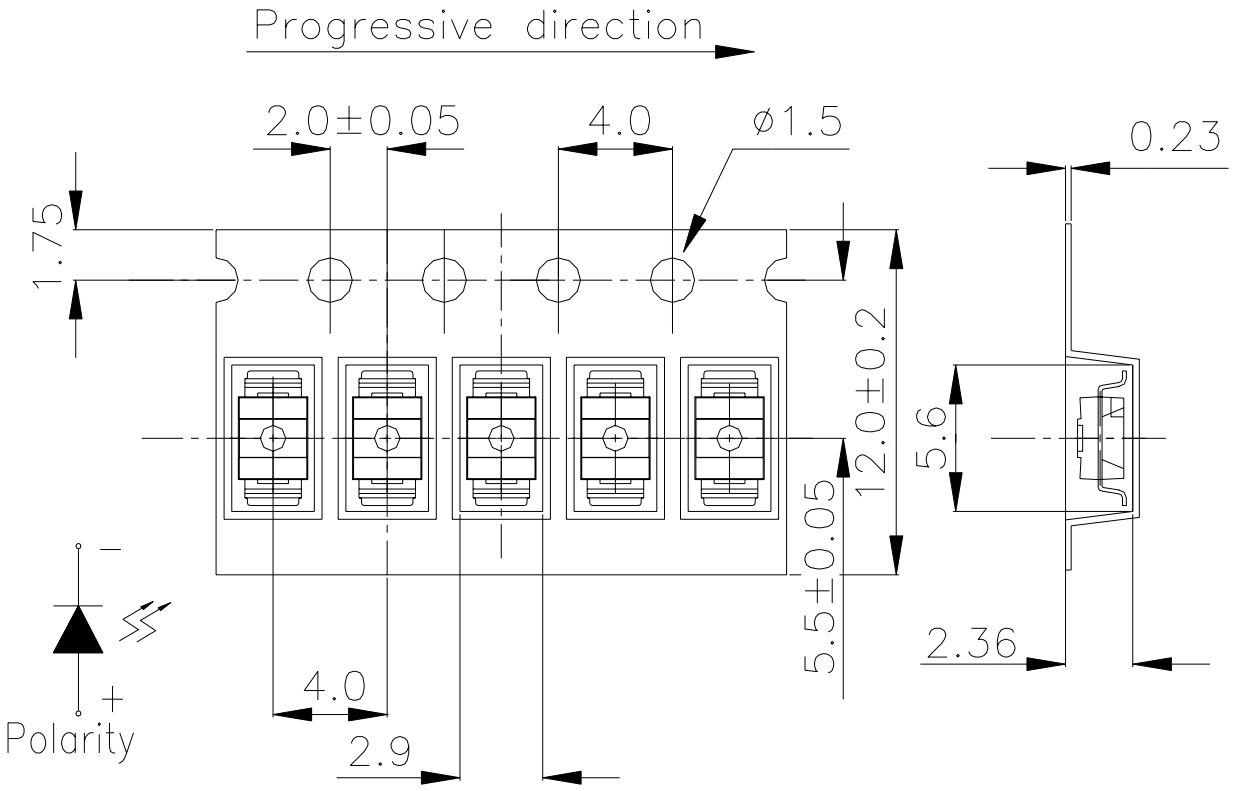


Reel Dimensions



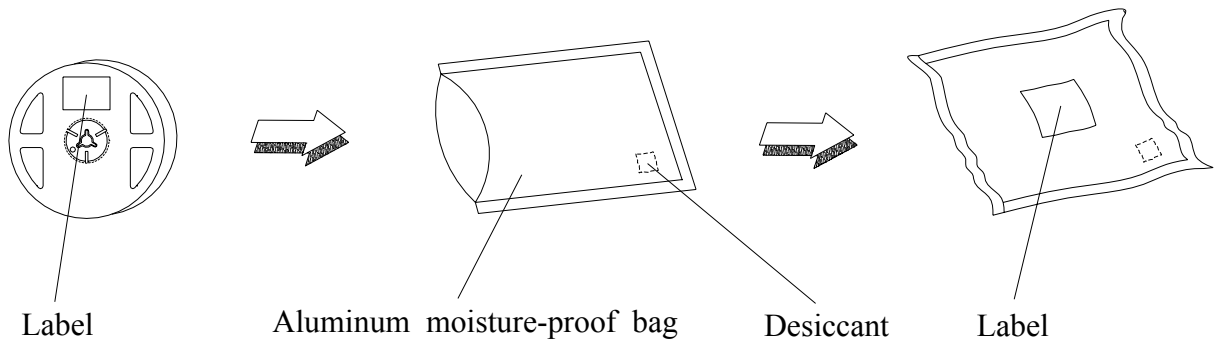
Note: Tolerances Unless Dimension ±0.1mm , Unit = mm

Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: Tolerances Unless Dimension ±0.1mm ,Unit = mm

Moisture Resistant Packaging



67-21 SUGC/S400-XX/TR10

Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.
Confidence level：90%
LTPD：10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260℃±5℃ Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100℃ 15min ∫ 5 min L : -40℃ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100℃ 5min ∫ 10 sec L : -10℃ 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100℃	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40℃	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I_F = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85℃/ 85%RH	1000 Hrs.	22 PCS.	0/1

Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

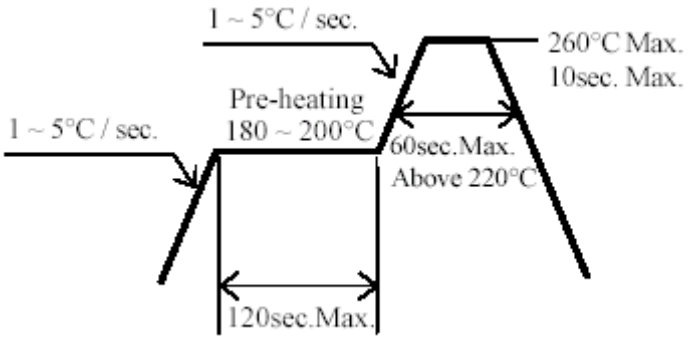
2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30 deg C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
Baking treatment : 60±5℃ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile

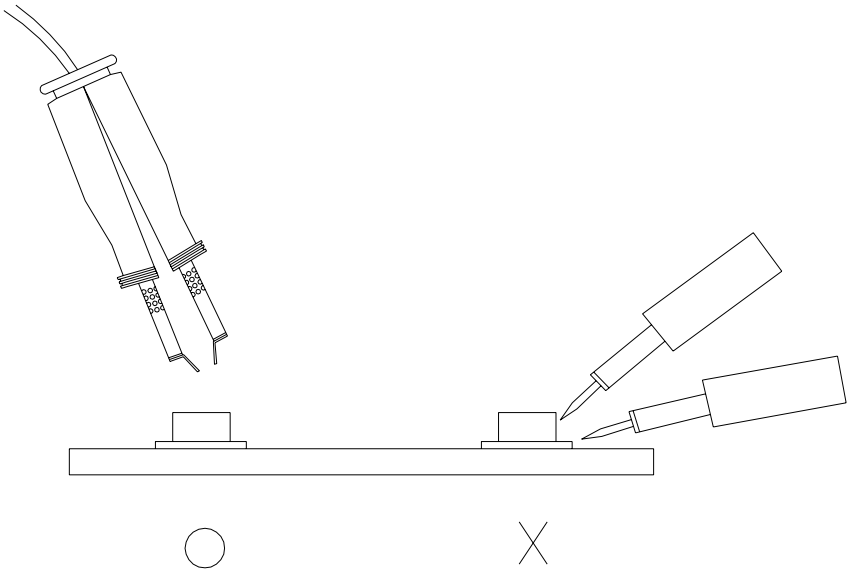


3.2 Reflow soldering should not be done more than two times.
3.3 When soldering, do not put stress on the LEDs during heating.
3.4 After soldering, do not warp the circuit board.
4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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